

TIM4201-4.0

Single Component Thermal Gap Filler

TIM4201-4.0 Thermally conductive gel is a thermal interface material with single-component. The material has some stress-strain value superior than the ultra-soft silicone sheet. It can be automatically dispensed and coated. It is the best heat dissipation solution when multiple chips share radiator and structures.

FEATURE

- High thermal conductivity, low thermal resistance
- Small Young modulus
- No silicone oil and pollution
- Excellent machinability

APPLICATIONS

- Semiconductors and radiators
- Power resistor and power base
- Temperature regulator and Assembly surface
- Thermoelectric cooling devices
- CPU and GPU

This series of products are environmentally compliant with RoHS 2.0, halogen, and REACH standards

CONDITIONS: Storage in the darkness

STORAGE TEMPERATURE: $\leq 30\text{ }^{\circ}\text{C}$

STORAGE HUMIDITY: $\leq 70\%$

SHELF LIFE:

Under storage conditions: 1 year

STORAGE CONDITIONS:

- In order to ensure that the products maintain the quality, it should be kept in low temperature with dry and sealed environment or container.
- During the storage period, make sure that the container is sealed to protect electrical performance from external contaminants.
- PACKING SPECIFICATIONS: 30cc/50cc/300cc

PROPERTIES

Item	Parameter	Unit	Test Method
Color	Light blue	-	Visual
Density	3.1	g/cc	ASTM D 792
Extrusion speed	≥ 30 (@90psi)	g/min	$\phi 2.41\text{mm}$ EFD Injection head
Minimum filling part	≤ 0.15	mm	--
Operation temperature	-50~150	$^{\circ}\text{C}$	IEC60068-2-14

THERMAL CHARACTERISTIC

Thermal Conductivity	4.0	W/m-K	ASTM D 5470
Thermal Resistance	≤ 0.07 (@40psi)	$^{\circ}\text{Cin}^2/\text{W}$	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown voltage	≥ 5	kV /mm	ASTM D 149
Volume Resistivity	$\geq 10^{10}$	$\Omega \cdot \text{cm}$	ASTM D 257